TECHCET GROUP LLC PRESENTS

CMP Consumables Update Suppliers, Markets, Applications

Bob Roberts – Axus Technology

BROBERTS@AXUSTECH.COM Рн: 704.577.8089

UNDER CONTRACT WITH:



Electronics Materials Information

TECHCET GROUP LLC

If we could first know where we are and where we are going, we could then better judge what to do and how to do it. Abraham Lincoln 1858



Electronics Materials Information

The value of the TECHCET Report therefore is in: **Risk Management**

TECHCET GROUP LLC

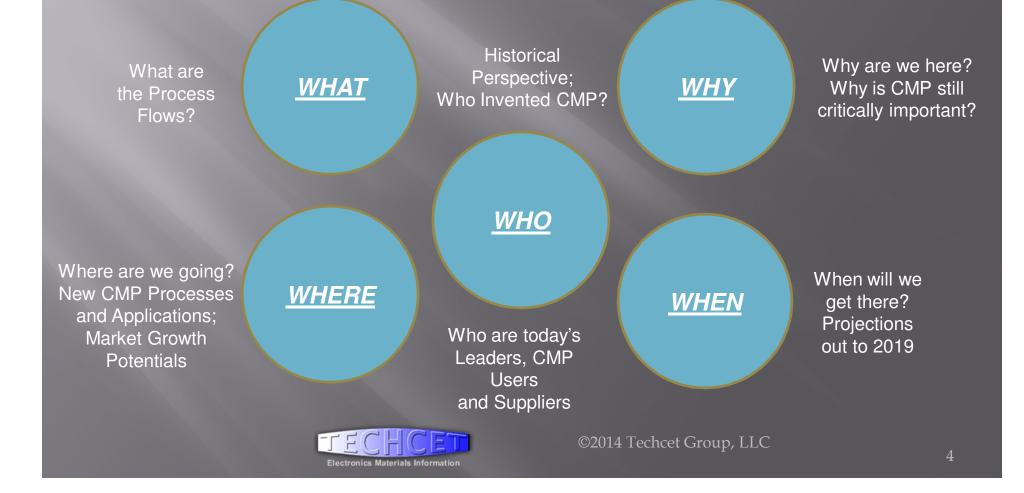
The More you can Learn From the Best Sources you can Find The more Capable you will become in:

Risk Management



Electronics Materials Information

From the Beginning, we set out to do Something Different this year



From the Beginning, we set out to do Something Different this year

The report was written to become the definitive resource for:

- The CMP User Community
- CMP Industry Strategists & Technicians
- CMP Supply Chain Managers
- and in addition:
 - Employees new to CMP it is a Technology Primer
 - New suppliers it indicates where opportunities are located
 - Investor Community it highlights market leaders & start-ups



Techcet CMP Consumables What is in this new report?

The CMP Industry Climate & Applications Analysis

- Nine Market Segments
- Slurries
- Pads
- Slurry Filters
 - **PVC Brushes**
- - Retaining Rings Equipment Suppliers Support & Service
- **Conditioning Disks**
- Cleaning Chemistries
- Each segment in the new TECHCET Report includes:
 - Executive Summary
 - Business Environment Analysis
 - Market Share Information
 - Projections into future years
 - Supplier Company Profiles extensive, in-depth



©2014 Techcet Group, LLC

Techcet CMP Consumables What is in this new report?

The Supplier Analysis (189) includes:

- Company name and contact information, date established
- Parent Company, ownership tree
- Global locations, manufacturing locations
- Websites applicable to CMP
- Company Overview, History, Current involvement in CMP
- Annual Sales Revenue; Total and CMP related
- CMP related products and applications
- Market share position
- Comments, discussion points, potential changes



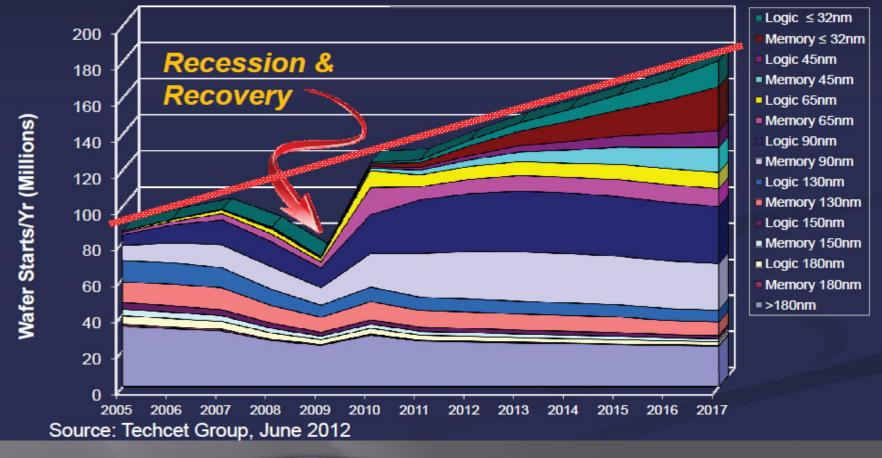
Techcet CMP Consumables What is in this new report?

- The University Research Program Analysis (40) includes:
 - University name and Location information
 - Program Chair or Technology Leader
 - Technology, Product, or Service Focus of this program
 - Website addresses, contact information
 - Overview of their program; direction of their research



CMP Consumables – 2005 to 2012 Dld Rews

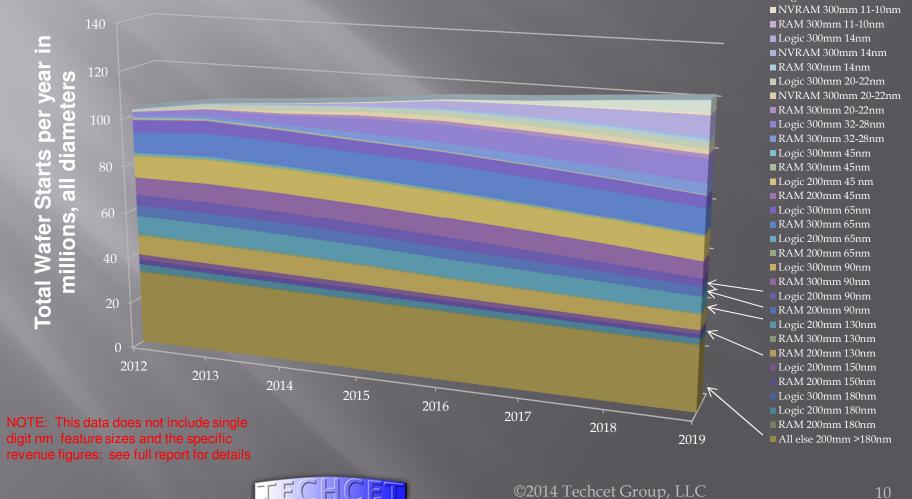
Annual Wafer Starts (200mm equivalents)





CMP Consumables – 2014-2019 **New News**

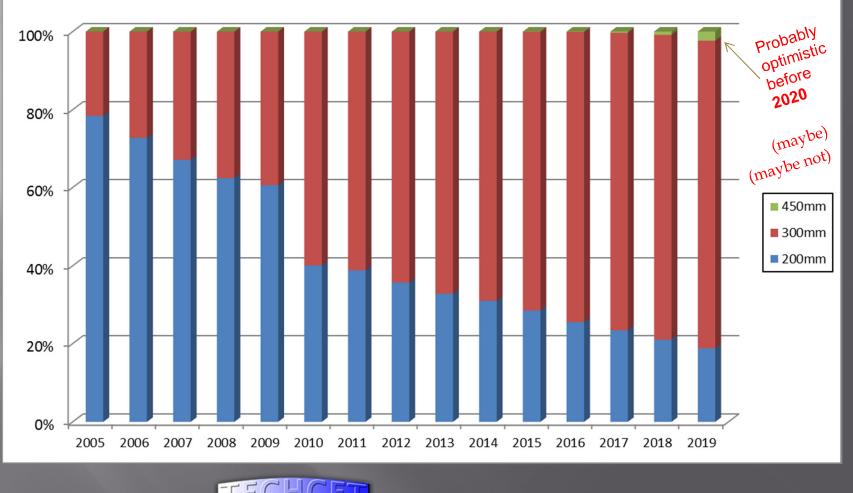
Annual Wafer Starts, by Technology, by Diameter



■ Logic 450mm 11-10nm ■ Logic 300mm 11-10nm

CMP Consumables – 2014-2019 New News

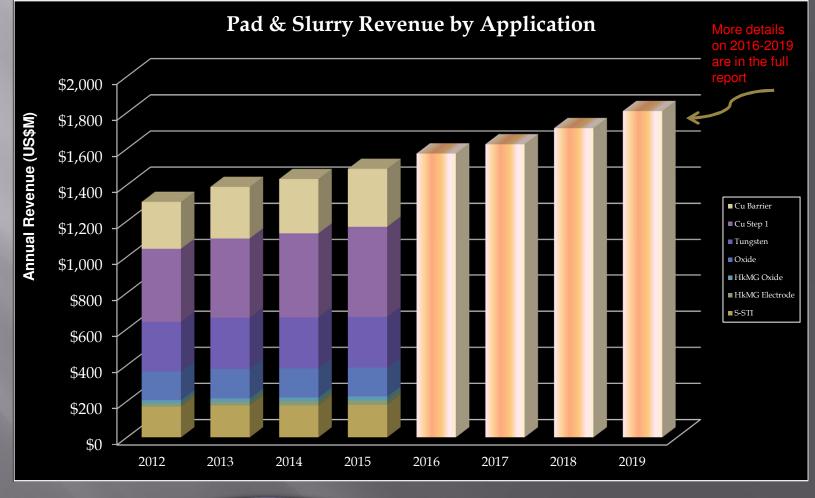
% Pad Revenue by Wafer Size: All Processes



Electronics Materials Information

©2014 Techcet Group, LLC

CMP Consumables – 2014 New News





©2014 Techcet Group, LLC

The Business of CMP – in a nutshell

- Older technologies their dominance is weakening
 - 200mm and smaller
 - 90nm (and larger) Logic and Ram
 - Tungsten and some ILD CMP processes
- Newer technologies their presence is growing
 - 300mm definitely
 - 450mm still some degree of speculation on timing
 - Expected to be the most expensive per-fab retooling the semiconductor industry has ever seen
 - ~ \$6B to \$10B US\$ for each fab!
 - 22nm and smaller (14nm going into production; 7nm, 5nm on the horizon)
 - Copper and Copper Barrier CMP processes
 - Some Selective STI growth continues
 - Discussions are ongoing about <u>single digit</u> nm feature sizes!



■ The Business of CMP – in a nutshell (continued)

- Growth in consumables revenue now comfortably above \$2B US\$
- Growth in Copper, Copper Barrier, some Selective STI applications
- 5-year CMP slurries and pads CAGR: 3.87% (driven by slurries)

IC Customer base is changing: Consolidation, Retraction

- Fewer customers, larger customers, a few are very large
 (and demanding!)
- Supplier companies face ASP challenges
 - Due to competition and customer "muscle"
- Diversification of 200mm fabs
 - MEMS growth rate outpacing overall IC market growth rate
 - Expected to be a \$20B US market by 2017
 - Specialized market and product niche



Who are the Slurry Suppliers? (listed by revenue estimates)

- Major supplier: Cabot Microelectronics Corporation (~ 36%)
- Then: Hitachi, FujiFilm, DA Nanomaterials, Fujimi, DOW
- Tungsten slurry not growing much; Copper slurry is surging
- Manufacturing in multiple country sites
 - Or forming collaborative or JV arrangements with Asian-based manufacturers
- Stand-alone Competitors in the Asian Region
 - China, Taiwan, South Korea
 - IP and patent infringements are not uncommon
 - Some are supported by major device fabs



■ Who are the Polishing Pad Suppliers? (listed by revenue estimates)

- 20 suppliers share the global TAM ~ \$720M US\$
- Major supplier: DOW Electronic Materials (but market share receding)
- Then: Cabot Microelectronics Corp.
- And: innoPad, Thomas West, NexPlanar, Fujibo
- Others: 3M, JSR, IV-Tech, KPX
- Manufacturing in multiple country sites
 - In order to get closer to the customer base
 - To mitigate risk of natural disasters
 - Establishment of secondary or tertiary manufacturing sites
- Stand-alone Competitors in the Asian Region
 - IP infringements are not uncommon



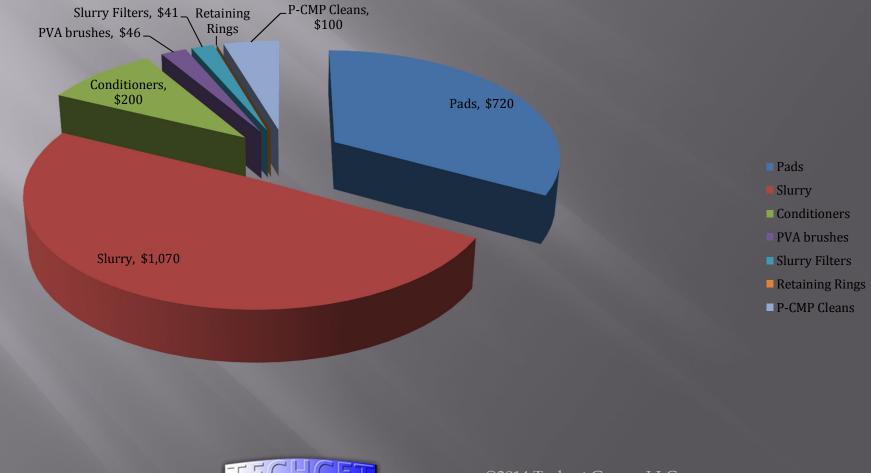
Who are the other CMP suppliers?

- Pad Conditioners
 - Market Size: ~ \$200M US\$
 - Leaders: 3M, Saesol, Kinik combined market share of 86%
- <u>P-CMP Cleaning Chemistries</u>
 - Market Size: ~ \$80M to \$120M US\$
 - Leaders: Air Products, ATMI (Entegris), combined share of 67%
- PVA Brushes
 - Market Size: ~ \$46M US\$
 - Leaders: ITW Rippey, Aion, Entegris, combined share of 91%
- Slurry Filters
 - Market Size: ~ \$41M US\$
 - Leaders: Pall, Entegris, combined market share of 87%



Market Sizes in Millions of US\$

Total CMP Consumables (less retaining rings) = \$2.177B US\$





©2014 Techcet Group, LLC

Looking for the New Normal

- From Solid State Technology, (March 12, 2014) "The Semiconductor Industry Association (SIA) today announced that worldwide sales of semiconductors reached \$26.28 billion for the month of January 2014, an increase of 8.8 percent from January 2013 when sales were \$24.15 billion, <u>marking the industry's highestever January sales total and the largest year-to-year increase in nearly three years</u>... sales in the Americas increased by 17.3 percent compared to last January.
- From Alix Partners (March 12, 2014) "Companies throughout the industry continue to grapple with several challenges, including <u>soft macroeconomic market</u> <u>environments</u> in key geographies, <u>intense competition</u>, <u>pricing pressure</u>, and short and <u>costly product life cycles</u>. Combined Sales, General, and Admin expenses (SG&A) and R&D spending increased 35% the past three years."
- From PWC Global, (March 12, 2014) "Current (semiconductor) market conditions and <u>outlooks are mixed</u> for the next few years, largely because of the fragile global economic outlook."

Which one is the New Normal?



©2014 Techcet Group, LLC

Techcet CMP Consumables Update: 3rd Quarter 2014 (2nd quarter numbers)

- Actual performance numbers from the supplier community are limited to the public and not typically shared
- Data from publically traded user companies is available
 - We can examine this information and draw conclusions on the health of the consumable supplier community
 - based upon quarter-to-quarter performance
 - Intel, Samsung, Qualcomm, SK Hynix, Texas Instruments, Renesas, Infineon, NXP, Freescale, all reported 2nd quarter revenue up at least 4% over 1st quarter (some as high at 8% to 10%)
 - Toshiba, and Micron are the only companies reporting negative growth in 2nd quarter results versus their 1st quarter results.
 - However, that negativity was less than they expected.
- Many predictions for 2015 growth performance are similar to the performance being seen in 2014.

Research sources: Gartner, SI Stats, WSTS, IMF

(WhatWeThinkWeKnow)

Ceria, Cerium Oxide

- Continues adaptations in STI and ILD applications
- It is price sensitive, source sensitive, supply sensitive, defectivity sensitive

450mm "Intel, ASML, AMAT slow down their migration to 450mm wafers." from Seeking Alpha, March 14, 2014

- - Indications are that projecting out 5 years...(or more!)
 - 24% of total wafer starts will still be 200mm (or smaller)
 - 75% of total wafer starts will be 300mm
 - Probably 1% (or less) will be at 450mm
- Copper and Copper Barrier continue to grow
 - Offering opportunities for innovative suppliers
- At 22nm and below:
 - <u>all</u> suppliers in <u>all</u> CMP segments must devote time, effort, research, and manufacturing improvements to reach the defectivity requirements or risk extinction.



(WhatWeThinkWeKnow)

- At 22nm and below (continued):
 - "Gate Last" for high performance logic followed possibly by other logic, perhaps flash, and then other memory going this direction
 - Metal of choice at 22nm and below
 - Aluminum? What about polishing issues? (smears, humps, comet trails)
 - Tungsten? Will it play a significant role? (alternative to aluminum?)
 - How does either one affect CMP slurries and pads?
- Significant Growth Moves/Changes at Consumables Manufacturers
 - Entegris takes over ATMI
 - 3M strong moves in filters and pad conditioners
 - Some smaller, innovative pad and slurry manufacturers gaining foothold (copper)



Techcet CMP Consumables – Beyond

(WhatWeNeedToKnow)

- Alternative Technologies
 - Nanowires
 - Carbon nanotubes
 - Graphene
 - Vacuum Transistors
 - "POET" or Planar Opto-Electronic Technology
- How do these technologies affect the implementation of CMP principles and practices?
- What changes will be needed in CMP consumables?
- When will they have an effect on a manufacturing scale?
- Who will be the technology leaders?



The Resource for: The CMP User Community, CMP Industry Strategists & Technicians, CMP Supply Chain Managers

- New, Expanding Applications for CMP
 - TSV in FEOL, MEOL, BEOL applications
 - MEMS incredible number of applications
 - LED GaN on silicon substrates
 - Nanotechnology
 - MicroMachining
- Consolidations Changes
 - Applied Materials and TEL
 - Entegris and ATMI
 - More supplier consolidations can be expected
 - Seemingly inevitable when:
 - the customer count shrinks
 - ASP pressures increase
 - Technology growth begins to soften (Tungsten, and some ILD applications)
 - IBM may remove itself from device manufacturing or partner (GF?)



The Resource for: The CMP User Community, CMP Industry Strategists & Technicians, CMP Supply Chain Managers

Summary

- <u>CMP related technologies in general</u>, when examined as a Technology Sector of the overall semiconductor industry look to be <u>relatively strong</u> for the next five year period – driven by copper.
 - 2014 Mid-Year reports show solid year-over-year growth in IC shipments (25+%) and manufacturing equipment bookings (25+%)
- Closer investigation clearly indicates a <u>weakening trend in Tungsten</u> and some ILD applications, and a diminishing volume of 200mm wafer starts.
- The variety of applications of <u>CMP technologies</u> is <u>growing in MEMS</u>, MOEMS, TSV, and other nanotechnologies.
- At 22nm and below, <u>defectivity</u> needs to be the <u>primary concern</u> of everyone in the CMP Consumables Market sector (users and suppliers).
- Investments into <u>450mm technology</u> are being made but <u>pausing</u>.
 - The schedules for wholesale introduction and respectable ROI are still vague; with <u>impacts upon pads more than slurry</u> at this point.
- Supplier consolidations are expected to continue.



The Resource for: The CMP User Community, CMP Industry Strategists & Technicians, CMP Supply Chain Managers

Techcet Group LLC

- Lita Shon-Roy, President/CEO
- Karey Holland, PhD, Chief Technologist & Future Technologies Analyst
- Mike Fury, PhD, Sr. Technology Analyst CMP Consumables
- <u>Chris Michaluk</u>, Dir. of Bus. Development & Sr. Technology Analyst -Metals
- Yu Bibby, PhD, Sr. Technology Analysis; Process Chemicals, China Metals & Materials
- Ralph Butler, Sr. Technology Analyst Silicon Wafers
- □ <u>Gerald Elder</u>, PhD, Sr. Technology Analyst Photoresist, Ancillaries, Gases
- □ Jiro Hanaue, Director, Sr. Technology Analyst Equipment Components
- Steve Holland, PhD, Technology & Process Training
- John Housley, Business Operations Advisor
- Bob Roberts, Technology and Market Analyst CMP Consumables



The Resource for: The CMP User Community, CMP Industry Strategists & Technicians, CMP Supply Chain Managers

Techcet Group LLC - Special Thanks to...

- Lita Shon-Roy, President/CEO
- Karey Holland, PhD, Chief Technologist and Future Technologies Analyst
- Mike Fury, PhD, Senior Technology Analyst CMP Consumables
- Chris Michaluk, Director of Business Development and Senior Technology Analyst – Metals

Axus Technology

Paul Feeney, Director of Process Development



The Resource for: The CMP User Community, CMP Industry Strategists & Technicians, CMP Supply Chain Managers

The Techcet Group, LLC

- The 2014 Techcet Report on CMP Consumables & Market Analysis
 - 12 Sections, over 600 pages
 - Overviews and Analyses of:
 - 9 CMP Market Segments
 - 189 CMP Consumable Suppliers
 - 13 CMP Equipment Suppliers
 - 40 College/University CMP programs

To order, contact: Chris Michaluk

- Ordering information: <u>www.Techcet.com</u>
- Phone Orders:

- 480.336.2160
- Fax Orders: 480.275.3101
- Contact: <u>CMichaluk@Techcet.com</u>



